

Description

The series of devices uses **Super Trench II** technology that is uniquely optimized to provide the most efficient high frequency switching performance. Both conduction and switching power losses are minimized due to an extremely low combination of $R_{DS(ON)}$ and Q_g . This device is ideal for high-frequency switching and synchronous rectification.

Application

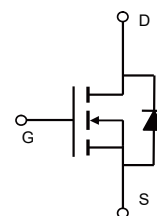
- DC/DC Converter
- Ideal for high-frequency switching and synchronous rectification

General Features

- $V_{DS} = 100V, I_D = 150A$
 $R_{DS(ON)} = 3.0m\Omega$, typical (TO-220) @ $V_{GS} = 10V$
 $R_{DS(ON)} = 2.8m\Omega$, typical (TO-263) @ $V_{GS} = 10V$
- Excellent gate charge x $R_{DS(on)}$ product(FOM)
- Very low on-resistance $R_{DS(on)}$
- 175 °C operating temperature
- Pb-free lead plating



TO-220



Schematic

Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
VST10N030	VST10N030-TC	TO-220	-	-	-

Absolute Maximum Ratings ($T_c = 25^\circ C$ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V_{DS}	100	V
Gate-Source Voltage	V_{GS}	± 20	V
Drain Current-Continuous	I_D	150	A
Drain Current-Continuous($T_c = 100^\circ C$)	$I_D(100^\circ C)$	113	A
Pulsed Drain Current	I_{DM}	600	A
Maximum Power Dissipation	P_D	240	W
Derating factor		1.6	W/ $^\circ C$
Single pulse avalanche energy (Note 3)	E_{AS}	1280	mJ
Operating Junction and Storage Temperature Range	T_J, T_{STG}	-55 To 175	$^\circ C$

Thermal Characteristic

Thermal Resistance,Junction-to-Case	$R_{\theta JC}$	0.63	$^{\circ}\text{C/W}$
Thermal Resistance,Junction-to-Ambient ^(Note 1)	$R_{\theta JA}$	60	$^{\circ}\text{C/W}$

Electrical Characteristics ($T_C=25^{\circ}\text{C}$ unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit	
Off Characteristics							
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =250μA	100		-	V	
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =100V, V _{GS} =0V	-	-	1	μA	
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±20V, V _{DS} =0V	-	-	±100	nA	
On Characteristics							
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =250μA	2.0	3.0	4.0	V	
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =10V, I _D =75A	TO-220	-	3.0	3.5	mΩ
			TO-263		2.8	3.5	mΩ
Gate resistance	R _G		-	2.3	-	Ω	
Forward Transconductance	g _{FS}	V _{DS} =5V, I _D =75A	80	-	-	S	
Dynamic Characteristics (Note2)							
Input Capacitance	C _{iss}	V _{DS} =50V, V _{GS} =0V, F=1.0MHz	-	9752	-	PF	
Output Capacitance	C _{oss}		-	820	-	PF	
Reverse Transfer Capacitance	C _{rss}		-	40	-	PF	
Switching Characteristics (Note 2)							
Turn-on Delay Time	t _{d(on)}	V _{DD} =50V, I _D =75A V _{GS} =10V, R _G =1.6Ω	-	27	-	nS	
Turn-on Rise Time	t _r		-	17	-	nS	
Turn-Off Delay Time	t _{d(off)}		-	55	-	nS	
Turn-Off Fall Time	t _f		-	19	-	nS	
Total Gate Charge	Q _g	V _{DS} =50V, I _D =75A, V _{GS} =10V	-	137	-	nC	
Gate-Source Charge	Q _{gs}		-	49.3		nC	
Gate-Drain Charge	Q _{gd}		-	31.3		nC	
Drain-Source Diode Characteristics							
Diode Forward Voltage	V _{SD}	V _{GS} =0V, I _S =75A	-		1.2	V	
Diode Forward Current	I _S		-	-	150	A	
Reverse Recovery Time	t _{rr}	T _J = 25°C, I _F = 75A di/dt = 100A/μs(Note3)	-	100	-	nS	
Reverse Recovery Charge	Q _{rr}		-	268	-	nC	

Notes:

1. The value of $R_{\theta JA}$ is measured with the device mounted on 1in2 FR-4 board with 2oz. Copper, in a still air environment with $T_A = 25^{\circ}\text{C}$.
2. Guaranteed by design, not subject to production
3. EAS condition : $T_J=25^{\circ}\text{C}, V_{DD}=50V, V_{GS}=10V, L=0.5mH, R_g=25\Omega$

Typical Electrical and Thermal Characteristics

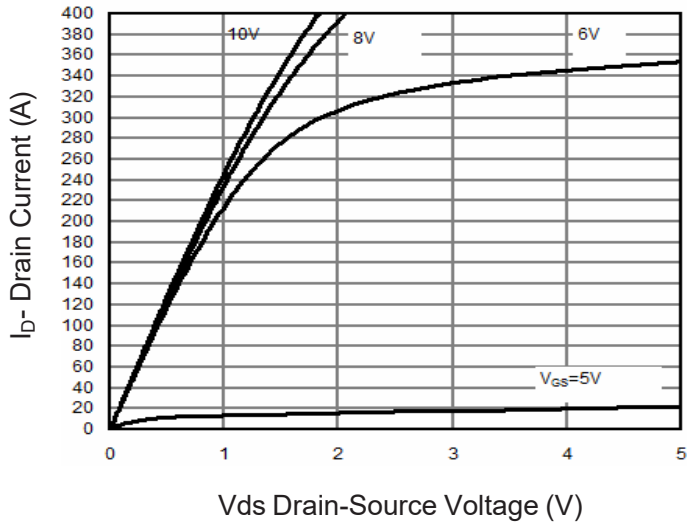


Figure 1 Output Characteristics

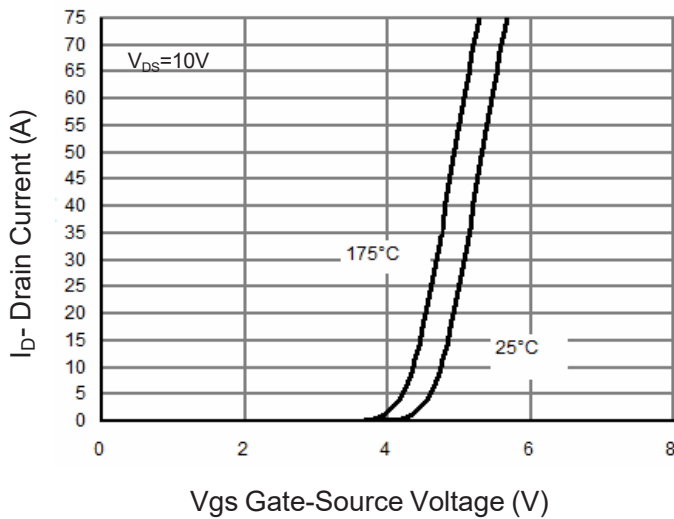


Figure 2 Transfer Characteristics

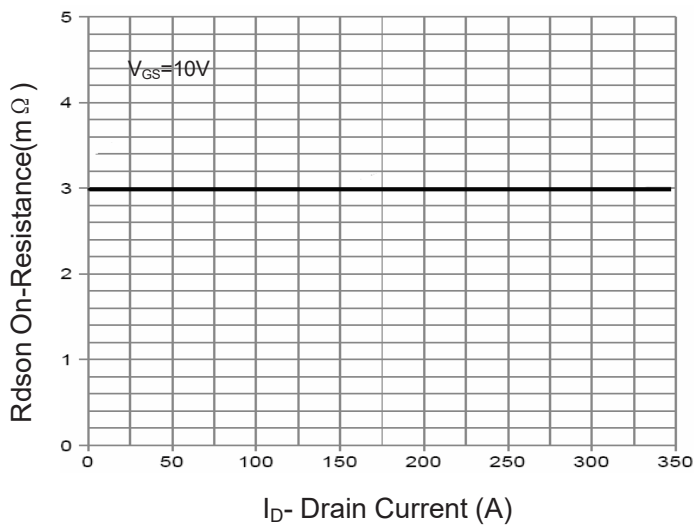


Figure 3 Rdson- Drain Current

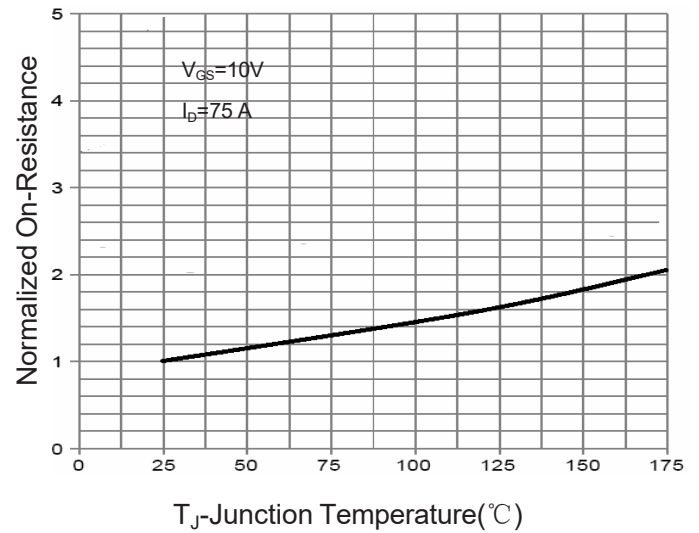


Figure 4 Rdson-Junction Temperature

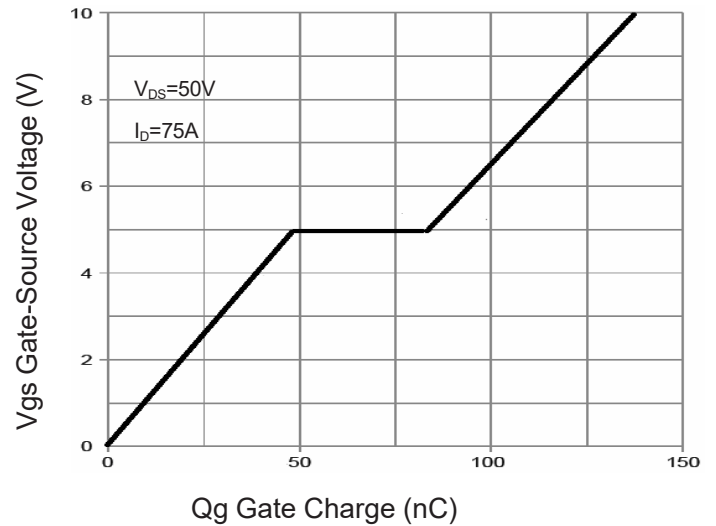


Figure 5 Gate Charge

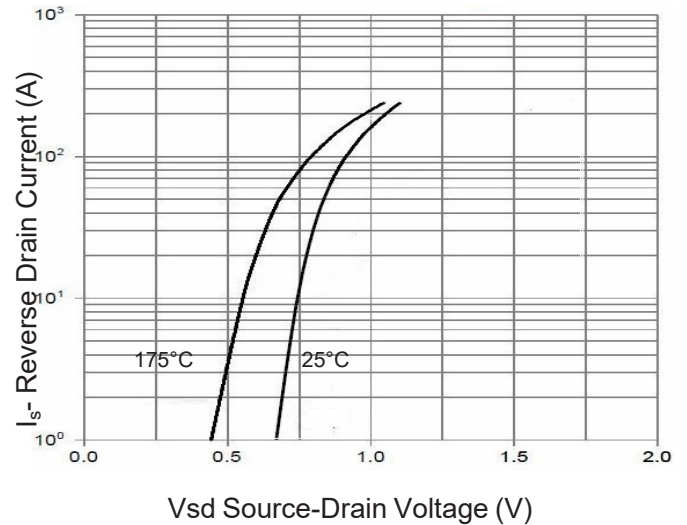
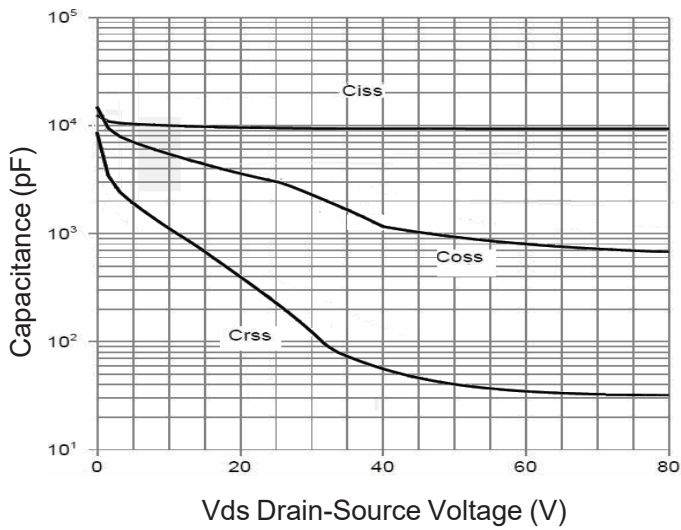
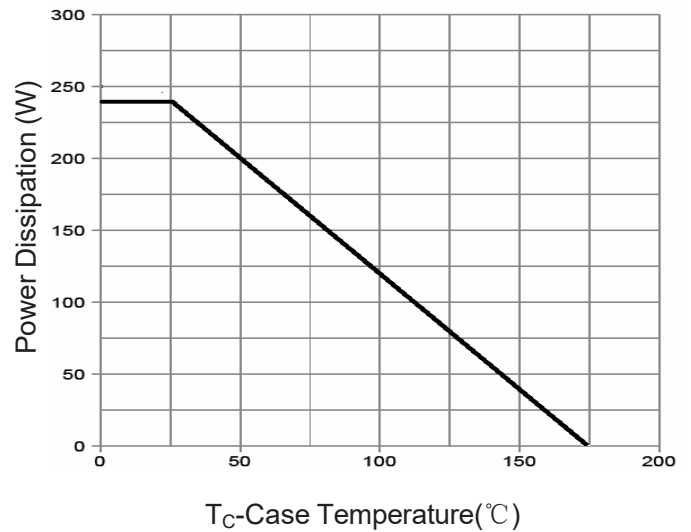
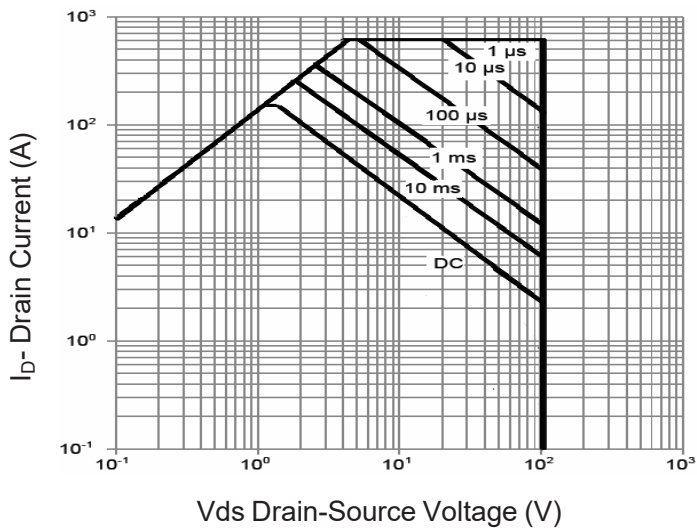
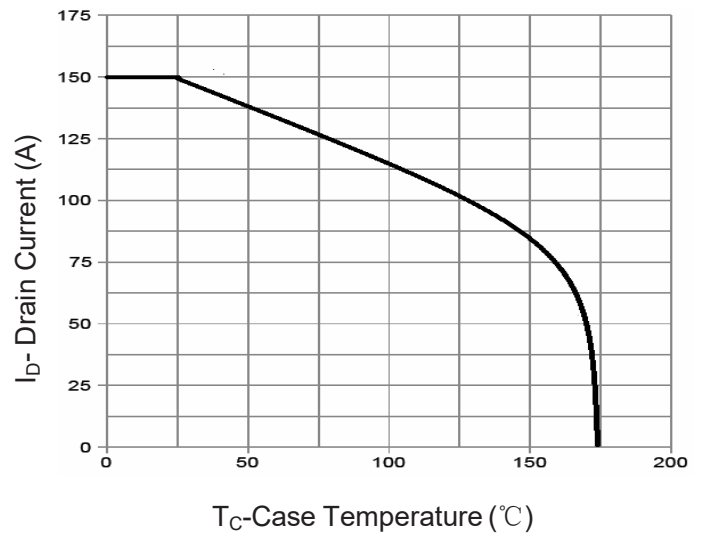
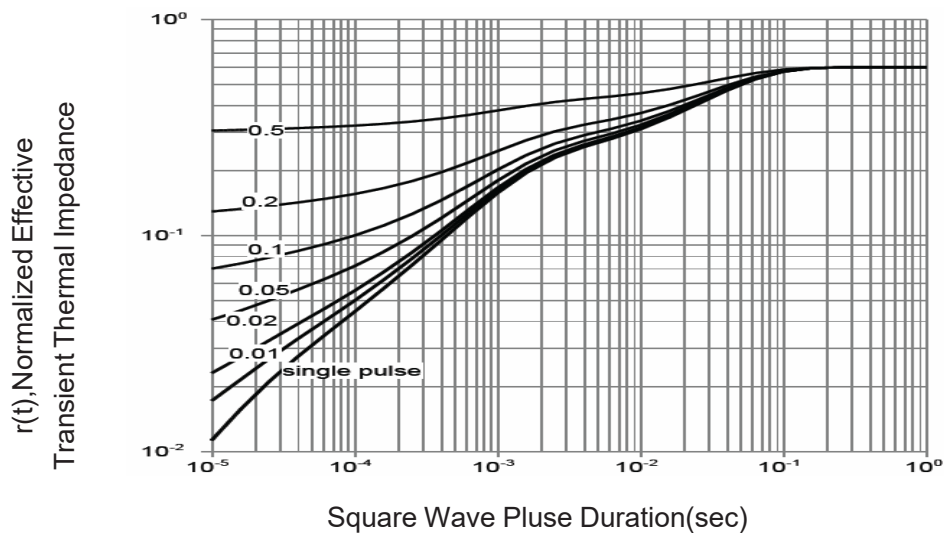


Figure 6 Source- Drain Diode Forward


Figure 7 Capacitance vs Vds

Figure 9 Power De-rating

Figure 8 Safe Operation Area

Figure 10 Current De-rating

Figure 11 Normalized Maximum Transient Thermal Impedance